Capacitive-Based Human Proximity Detection for System Wake-Up and Interrupt

Revision History

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- **Sheet Title:**
- **Size:**
- **Mod. Date:** 10/13/2014
- **File:** ISE4010_CoverSheet.SchDoc
- **Contact:**
- **http://www.ti.com**
- **http://www.ti.com/support**

**Project Title:**

**Designed for:**

**Public Release**

**Assembly Variant:**

**001**

**Drawn By:**

**Engineer:** Evan Cornell

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**2014**

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**Not in version control**

**SVN Rev:**

**Number:**

**Rev:**

**TID #:** TIDA-00220

**Orderable:** N/A

**Revision History:**

- **Revision:** E1
  - **Notes:** Original Release
- **Revision:** E2
  - **Notes:** Updated FDC Filter Values

**Components:**

- **5V USB**
- **5V**
- **3.3V**
- **MCU**
  - **I2C**
  - **FDC**
    - **(Cap - To - Dig. Proximity)**
  - **Temp. Sensor**
  - **EM Header**
    - **(Low-Power Radio)**
- **Backlight Controller**
- **PC**
- **UART Debug Data**
- **Capacitive Proximity Sensor**
- **5V USB**
- **3.3V**
- **SPI**
- **5V USB**
- **3.3V**
- **LDO**
- **SPI**
- **EM Header**
  - **(Low-Power Radio)**
- **LCD Screen**
  - **Backlight**
  - **Controller**
- **PC**
USB Connector & Protection

5V to 3.3V LDO

Communication Module Test Points

Reset & User Buttons

EM Connector for Wireless Connectivity

JTAG Interface & ESD Protection

Engineer:
Drawn By:
SVN Rev:
Not in version control
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